

Title (en)

METHOD FOR MAKING AN ANISOTROPIC CONDUCTIVE FILM WITH POINTED CONDUCTIVE INSERTS

Title (de)

HERSTELLUNGSVERFAHREN FÜR EINEN ANISOTROPISCHEN LEITERFILM MIT LEITENDEN EINSATZSTÜCKEN

Title (fr)

PROCEDE DE FABRICATION DE FILM CONDUCTEUR ANISOTROPE A INSERTS CONDUCTEURS POINTUS

Publication

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Application

**EP 03762727 A 20030702**

Priority

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Abstract (en)

[origin: WO2004006324A2] The invention concerns a method for making an anisotropic conductive film with pointed conductive inserts. The method comprises engraving at least one pattern (C1, K1) in a monocrystalline substrate (15) to form at least one cell (22, 26) having a base designed to form the contour of one end of an insert (23, 27). The formation of the pattern is designed to reveal at least one tip projecting in the base of the cell during engraving of the pattern in a crystallographic plane (100) of the substrate with planes (111) or (110) limiting the pattern. The invention is applicable to microconnectics.

IPC 1-7

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IPC 8 full level

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Citation (search report)

See references of WO 2004006324A2

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